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1. An electronic connector, comprising:  
 a heat generating electronic component capable of electronically coupling two data devices together; and  
 a housing positioned about said heat generating electronic component; said housing being made of a thermally conductive material; said housing being in thermal communication with said heat generating electronic component with heat being dissipating from said heat generating electronic component and through said housing.

2. The electronic connector of Claim 1, wherein said thermally conductive material is a thermally conductive net-shape moldable polymer composition.

3. The electronic connector of Claim 1, wherein said housing is injection molded.

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4. The electronic connector of Claim 1, wherein said heat generating electronic component is a semiconductor device.

5. The electronic connector of Claim 1, wherein said heat generating electronic component is a laser.

6. The electronic connector of Claim 1, wherein said electronic connector is an opto-electronic connector interface between fiber optic cable and electronic cable.

7. The electronic connector of Claim 2, wherein said thermally conductive composition includes a base matrix of a liquid crystal polymer material loaded with thermally conductive filler.

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8. The electronic connector of Claim 7, wherein said thermally conductive filler is selected from the group consisting of carbon fiber, aluminum, copper, boron nitride, alumina, magnesium and brass.

9. The electronic connector of Claim 1, wherein said electronic connector has a thermal conductivity of at least 30 W/m<sup>2</sup>K.

10. The electronic connector of Claim 1, wherein said housing is net-shape moldable.

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11. A method of forming an electronic connector, comprising the steps of:

providing a heat generating electronic component capable of electronically coupling two data devices together having a first port and a second port;

molding an outer housing of moldable thermally conductive polymer material around said heat generating electronic component leaving said first port and said second port of said heat generating electronic component exposed.

12. The method of Claim 11, wherein said moldable thermally conductive polymer material is a base matrix of liquid crystal polymer with thermally conductive filler therein.

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a<sub>3</sub> 13. The method of Claim 12, wherein said thermally conductive filler is selected from the group consisting of carbon fiber, aluminum, copper, boron nitride, alumina, magnesium, nickel and brass.

14. The method of Claim 11, further comprising the step of:  
electromagnetically shielding said heat generating electronic component by surrounding said heat generating electronic component with an electromagnetically shielding material.

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a<sub>3</sub> 15. The method of Claim 14, wherein said electromagnetically shielding material is metallic filler selected from the group consisting of aluminum, copper, alumina, magnesium and brass.

16. The method of Claim 11, wherein said housing is overmolded about said electronic component.